502012903 08/03/2012

PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Sandeep Kumar GOEL	07/10/2012

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Co., Ltd.
Street Address:	No. 8, Li-Hsin Road 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13546033

CORRESPONDENCE DATA

Fax Number: 2156894905 **Phone**: 215-979-1000

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Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

via US Mail.

Correspondent Name: DUANE MORRIS LLP (TSMC) IP DEPARTMENT

Address Line 1: 30 SOUTH 17TH STREET

Address Line 4: PHILADELPHIA, PENNSYLVANIA 19103-4196

ATTORNEY DOCKET NUMBER: 2011.1114/1085.925

NAME OF SUBMITTER: Mark C. Comtois

Total Attachments: 2

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PATENT

REEL: 028716 FRAME: 0365

Serial No. 13/546,033 filed July 11, 2012

ATTORNEY DOCKET NO.: 2011.1114/1085.925

ASSIGNMENT AND AGREEMENT

For value received, I, Sandeep Kumar GOEL, hereby transfers to Taiwan Semiconductor Manufacturing Co., Ltd., with its principal place of business located at No. 8, Li-Hsin Road 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China, and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to SYSTEM AND METHOD FOR TESTING STACKED DIES, described in a non-provisional application claiming priority thereto and under any and all Letters Patent and any divisions, continuations, continuations-in-part, reexamination certificates, reissues, and extensions thereof, or claiming priority therefrom that may be granted in the United States for said inventions; and I also concurrently hereby sell, assign and transfer to Taiwan Semiconductor Manufacturing Co., Ltd. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

I authorize Taiwan Semiconductor Manufacturing Co., Ltd. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from me, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

I hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Taiwan Semiconductor Manufacturing Co., Ltd. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

I request that any and all patents for said inventions be issued to Taiwan Semiconductor Manufacturing Co., Ltd. in the United States and in all countries foreign to the United States, or to such nominees as Taiwan Semiconductor Manufacturing Co., Ltd. may designate.

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ATTORNEY DOCKET NO.: 2011.1114/1085.925

I agree that, when requested, I shall, without charge to Taiwan Semiconductor Manufacturing Co., Ltd. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

Inventor

Dated: July 10, 2012

Sandeep Kumar GOEL

Residence:

3420 Finnian Way, Unit 404, Dublin, California 94568, United States of America

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RECORDED: 08/03/2012

PATENT REEL: 028716 FRAME: 0367